# <u>TOSHIBA</u>

TOSHIBA Power Transistor Module Silicon NPN&PNP Epitaxial Type (Six Darlington Power Transistors inOne)

# MP6301

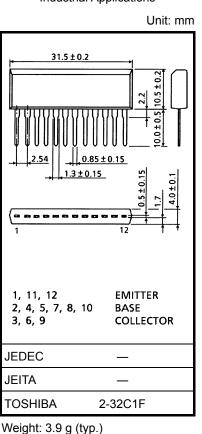
#### High Power Switching Applications 3-Phase Motor Drive and Bipolar Drive of Pulse Motor

- Small package by full molding (SIP 12 pins)
- High collector power dissipation (6-device operation) :  $P_T = 4.4 \text{ W} (T_a = 25^{\circ}\text{C})$
- High collector current: I<sub>C</sub> (DC) = ±3 A (max)
- High DC current gain:  $h_{FE} = 2000 \text{ (min)} (V_{CE} = \pm 2 \text{ V}, I_C = \pm 1 \text{ A})$

#### Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rat	Unit	
		Symbol	NPN	PNP	Offic
Collector-base voltage		V <sub>CBO</sub>	100	-100	V
Collector-emitter voltage		V <sub>CEO</sub>	80	-80	V
Emitter-base voltage		V <sub>EBO</sub>	8	-8	V
Collector current	DC	Ι <sub>C</sub>	3	-3	А
	Pulse	I <sub>CP</sub>	5	-5	~
Continuous base current		Ι <sub>Β</sub>	0.5	-0.5	А
Collector power dissipation (1-device operation)		P <sub>C</sub>	2.0		W
Collector power dissipation (6-device operation)		Ρ <sub>T</sub>	4.4		W
Junction temperature		Тј	150		°C
Storage temperature range		T <sub>stg</sub>	-55 to 150		°C

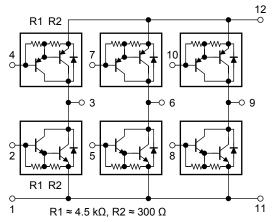
Industrial Applications



Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

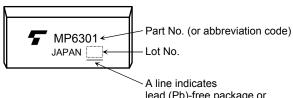
Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### Array Configuration



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#### Marking



A line indicates lead (Pb)-free package or lead (Pb)-free finish.

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit	
Thermal resistance from junction to ambient	ΣR <sub>th (j-a)</sub>	28.4	°C/W	
(6-device operation, Ta = 25°C)				
Maximum lead temperature for soldering purposes	TL	260	°C	
(3.2 mm from case for 10 s)				

#### Electrical Characteristics (Ta = 25°C) (NPN transistor)

Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Collector cut-off current		I <sub>CBO</sub>	V <sub>CB</sub> = 100 V, I <sub>E</sub> = 0 A	—	—	20	μA
Collector cut-off cu	rrent	ICEO	V <sub>CE</sub> = 80 V, I <sub>B</sub> = 0 A	_	_	20	μA
Emitter cut-off curre	ent	I <sub>EBO</sub>	V <sub>EB</sub> = 8 V, I <sub>C</sub> = 0 A	0.8	_	4.0	mA
Collector-base brea	akdown voltage	V (BR) CBO	I <sub>C</sub> = 1 mA, I <sub>E</sub> = 0 A	100	_	_	V
Collector-emitter bi	reakdown voltage	V (BR) CEO	I <sub>C</sub> = 10 mA, I <sub>B</sub> = 0 A	80	_	_	V
DC ourrent goin		h <sub>FE (1)</sub>	V <sub>CE</sub> = 2 V, I <sub>C</sub> = 1 A	2000	_	_	
DC current gain		h <sub>FE (2)</sub>	V <sub>CE</sub> = 2 V, I <sub>C</sub> = 2 A	1000	_	_	
Caturation welters	Collector-emitter	V <sub>CE (sat)</sub>	I <sub>C</sub> = 2 A, I <sub>B</sub> = 4 mA	_	_	1.8	v
Saturation voltage	Base-emitter	V <sub>BE (sat)</sub>	I <sub>C</sub> = 2 mA, I <sub>B</sub> = 4 mA	_	_	2.3	
Transition frequency		fT	V <sub>CE</sub> = 2 V, I <sub>C</sub> = 0.5 A	_	100	_	MHz
Collector output capacitance		C <sub>ob</sub>	V <sub>CB</sub> = 10 V, I <sub>E</sub> = 0 A, f = 1 MHz	_	20	_	pF
Switching time Sto	Turn-on time	t <sub>on</sub>	$\begin{array}{c} \text{Output} \\ \text{Input} \\ \text{20 } \mu \text{s} \\ \text{B2} \\ \text{B2} \\ \text{V}_{\text{CC}} = 30 \text{ V} \end{array}$	_	0.4	_	
	Storage time	t <sub>stg</sub>		_	3.0	_	μs
	Fall time	t <sub>f</sub>	$I_{B1} = -I_{B2} = 4 \text{ mA, duty cycle} \le 1\%$	_	0.6	_	

### Emitter-Collector Diode Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Forward current	I <sub>FM</sub>	—	_	_	3	А
Surge current	I <sub>FSM</sub>	t = 1 s, 1 shot	_	_	5	А
Forward voltage	VF	I <sub>F</sub> = 1 A, I <sub>B</sub> = 0 A	_	_	2.0	V
Reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> = 3 A, V <sub>BE</sub> = −3 V, dI <sub>F</sub> /dt = −50 A/µs	_	1	—	μs
Reverse recovery charge	Q <sub>rr</sub>		—	5	-	μC

#### Electrical Characteristics (Ta = 25°C) (PNP transistor)

Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Collector cut-off current		I <sub>CBO</sub>	V <sub>CB</sub> = -100 V, I <sub>E</sub> = 0 A	—	—	-20	μA
Collector cut-off cu	rrent	ICEO	V <sub>CE</sub> = -80 V, I <sub>B</sub> = 0 A	_	—	-20	μA
Emitter cut-off curr	ent	I <sub>EBO</sub>	V <sub>EB</sub> = -8 V, I <sub>C</sub> = 0 A	-0.8	—	-4.0	mA
Collector-base brea	akdown voltage	V (BR) CBO	I <sub>C</sub> = -1 mA, I <sub>E</sub> = 0 A	-100	_	_	V
Collector-emitter b	reakdown voltage	V (BR) CEO	I <sub>C</sub> = -10 mA, I <sub>B</sub> = 0 A	-80	—	_	V
DC ourrent goin		h <sub>FE (1)</sub>	V <sub>CE</sub> = -2 V, I <sub>C</sub> = -1 A	2000	_	_	
DC current gain		h <sub>FE (2)</sub>	$V_{CE} = -2 V, I_C = -2 A$	1000	_	_	—
Caturation voltage	Collector-emitter	V <sub>CE (sat)</sub>	I <sub>C</sub> = -2 A, I <sub>B</sub> = -4 mA	_	_	-1.8	v
Saturation voltage	Base-emitter	V <sub>BE (sat)</sub>	I <sub>C</sub> = -2 A, I <sub>B</sub> = -4 mA	_	_	-2.3	
Transition frequency		fT	$V_{CE} = -2 V, I_C = -0.5 A$	_	50	_	MHz
Collector output capacitance		C <sub>ob</sub>	V <sub>CB</sub> = -10 V, I <sub>E</sub> = 0 A, f = 1 MHz	_	30	_	pF
Switching time Stora	Turn-on time	t <sub>on</sub>	Input $\stackrel{I_{B2}}{\rightarrow}$	_	0.4	_	
	Storage time	t <sub>stg</sub>		_	1.8	—	μs
	Fall time	t <sub>f</sub>	20 µs −I <sub>B1</sub> = I <sub>B2</sub> = 4 mA, duty cycle ≤ 1%	_	0.4	_	

## Emitter-Collector Diode Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Forward current	I <sub>FM</sub>	—	_	_	3	А
Surge current	I <sub>FSM</sub>	t = 1 s, 1 shot	_	_	5	А
Forward voltage	VF	I <sub>F</sub> = 1 A, I <sub>B</sub> = 0 A	_	_	2.0	V
Reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> = 3 A, V <sub>BE</sub> = 3 V, dI <sub>F</sub> /dt = −50 A/µs	_	500	_	μs
Reverse recovery charge	Qrr		-	2.7	_	μC

#### **RESTRICTIONS ON PRODUCT USE**

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